

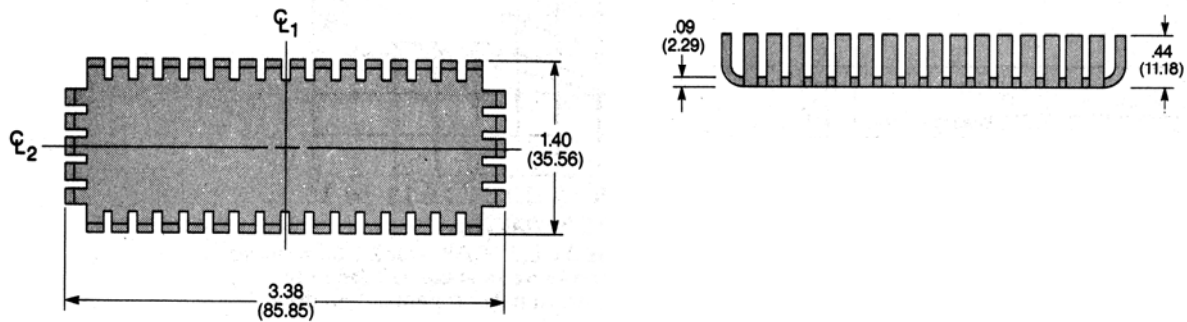
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP10 for Single TO-3 Outline

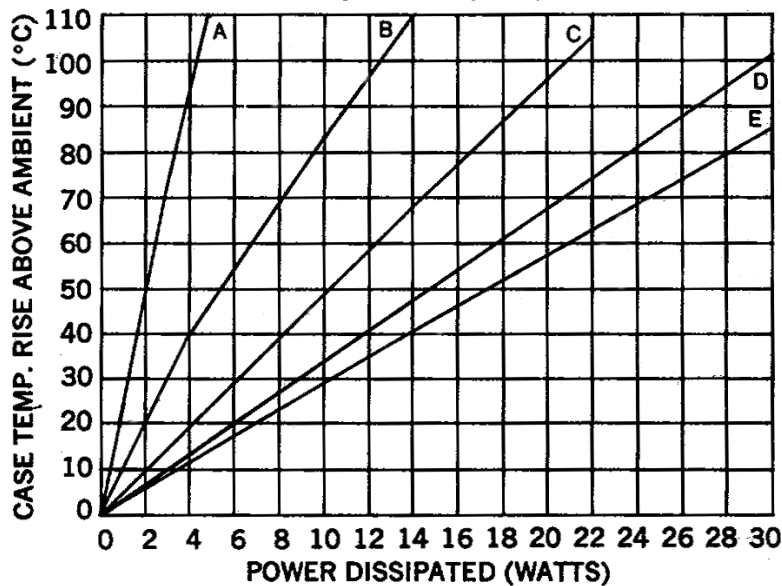
Natural Conv. ($^{\circ}\text{C}/\text{W}$): 8.7

Forced Air ($^{\circ}\text{C}/\text{W}$): 2.9

Mounting Envelope: 3.38" x 1.40" x .44"



UP10-TO3-CB w/2N3055 (TO-3) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

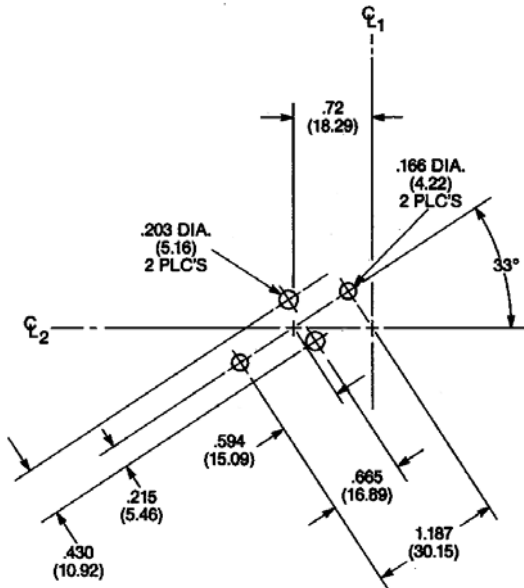
- Thermal Resistance Case to Sink is 0.1-0.3 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.4 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.

Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP10-TO3-U	UP10-TO3-CB	UP10-TO3-B	TO-3	37	24.0

HOLE PATTERNS

37. Hole pattern no. 432 accommodates TO-3s. Available in UP10 series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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